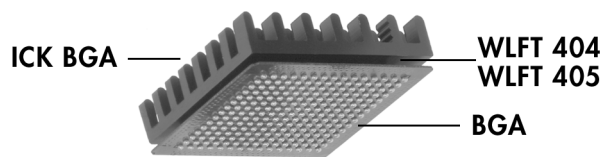


**Heatsinks for PGAs and BGAs**


- particularly suited for **B**all **G**rid **A**rrays
- heatsink dimensions match the respective BGA-type
- can be glued directly on the BGA component

<b>art. no.</b>  <b>ICK BGA 10 x 10</b> WLF ... 10 x 10		
<b>art. no.</b>  <b>ICK BGA 10 x 10 x 10</b> WLF ... 10 x 10		
<b>art. no.</b>  <b>ICK BGA 14 x 14</b> WLF ... 14 x 14		
<b>art. no.</b>  <b>ICK BGA 14 x 14 x 10</b> WLF ... 14 x 14		
<b>art. no.</b>  <b>ICK BGA 21 x 21</b> WLF ... 21 x 21		

**B 13**

Thermal conduct. foil WLFT 404/405 → E 5  
 Thermal conductive glue → E 14  
 Thermal conductive paste → E 12  
 Processor overview → B 2 - 7

SMD-heatsinks → B 25 - 27  
 Mounting material for semiconduct. → E 34 - 38  
 Hole pattern → A 21  
 Technical introduction → A 2 - 7